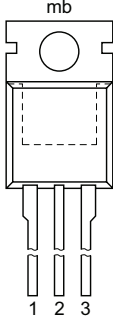
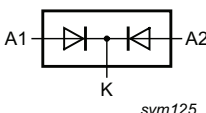


5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1		
2	K	cathode		
3	A2	anode 2		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV34-500	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

7. Marking

Table 4. Marking codes

Type number	Marking codes
BYV34-500	BYV34-500

8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		500	V
V_{RWM}	crest working reverse voltage		500	V
V_R	reverse voltage	$T_{mb} \leq 138\text{ }^{\circ}\text{C}$; DC	500	V
$I_{O(AV)}$	average output current	SQW; $\delta = 0.5$; $T_{mb} \leq 115\text{ }^{\circ}\text{C}$; both diodes conducting; Fig. 1; Fig. 2	20	A
I_{FRM}	repetitive peak forward current	SQW; $\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 115\text{ }^{\circ}\text{C}$; per diode	20	A
I_{FSM}	non-repetitive peak forward current	SIN; $t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; per diode	120	A
		SIN; $t_p = 8.3\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; per diode	132	A
T_{stg}	storage temperature		-40 to 150	$^{\circ}\text{C}$
T_j	junction temperature		150	$^{\circ}\text{C}$

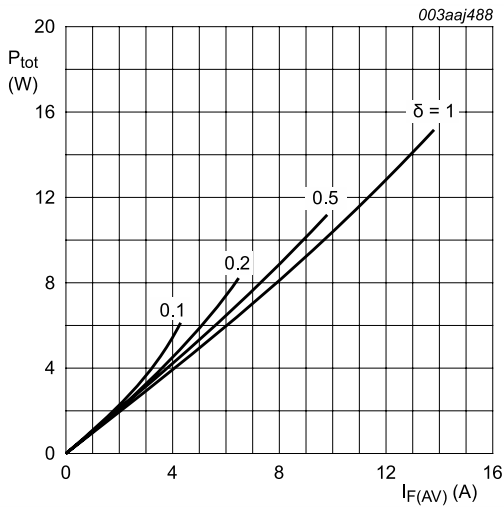


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; per diode; maximum values

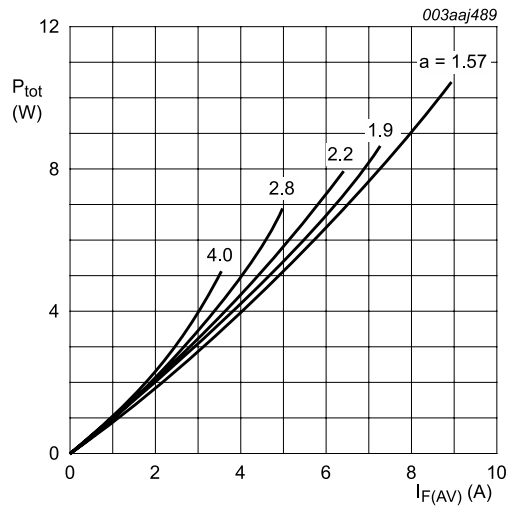


Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; per diode; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	with heatsink compound; both diodes conducting	-	-	1.6	K/W
		with heatsink compound; per diode; Fig. 3	-	-	2.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		-	60	-	K/W

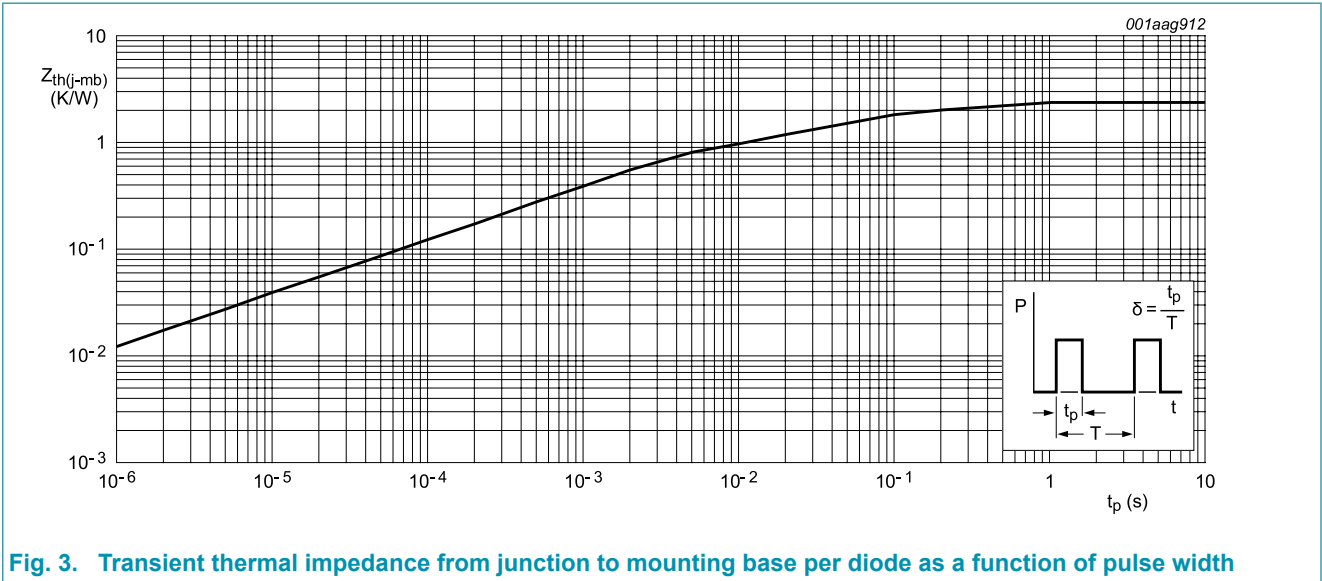
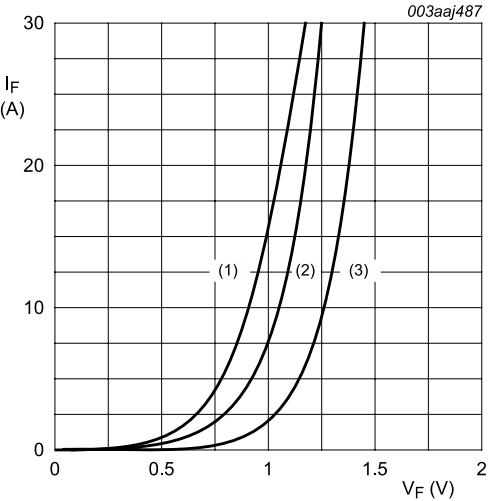


Fig. 3. Transient thermal impedance from junction to mounting base per diode as a function of pulse width

10. Characteristics

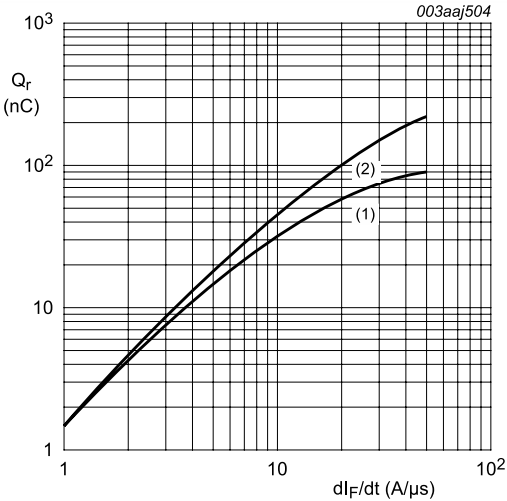
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 20 A; T _j = 25 °C; Fig. 4		-	1.1	1.35	V
		I _F = 10 A; T _j = 150 °C; Fig. 4		-	0.87	1.05	V
I _R	reverse current	V _R = 500 V; T _j = 25 °C		-	10	50	μA
		V _R = 500 V; T _j = 100 °C		-	0.2	0.6	mA
Dynamic characteristics							
Q _r	recovered charge	I _F = 2 A; V _R = 30 V; dI _F /dt = 20 A/μs; Fig. 5 ; Fig. 6		-	50	50	nC
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 6 ; Fig. 7		-	50	60	ns
I _{RM}	peak reverse recovery current	I _F = 10 A; V _R = 30 V; dI _F /dt = 50 A/μs; T _j = 100 °C; Fig. 6 ; Fig. 8		-	4	5	A
V _{FRM}	forward recovery voltage	I _F = 10 A; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 9		-	2.5	-	V



(1) T_J = 150 °C; typical values
(2) T_J = 150 °C; maximum values
(3) T_J = 25 °C; maximum values
V₀ = 0.94 V; R_s = 0.01 Ω

Fig. 4. Forward current as a function of forward voltage; per diode



(1) I_F = 2 A; T_J = 25 °C
(2) I_F = 20 A; T_J = 25 °C

Fig. 5. Recovered charge as a function of rate of change of forward current; per diode; maximum values

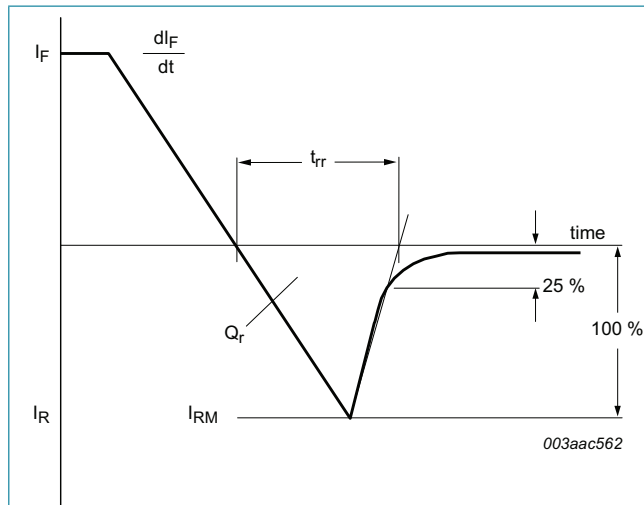
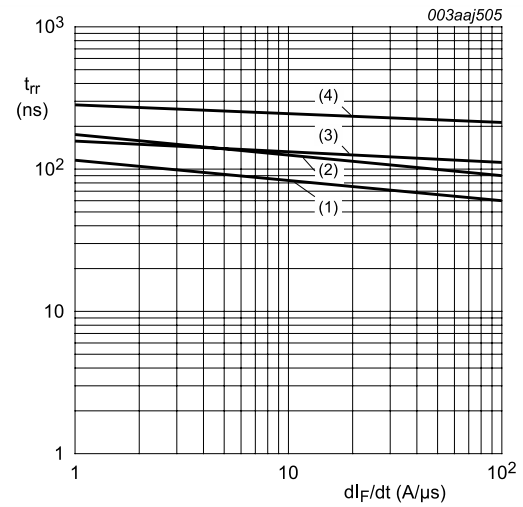
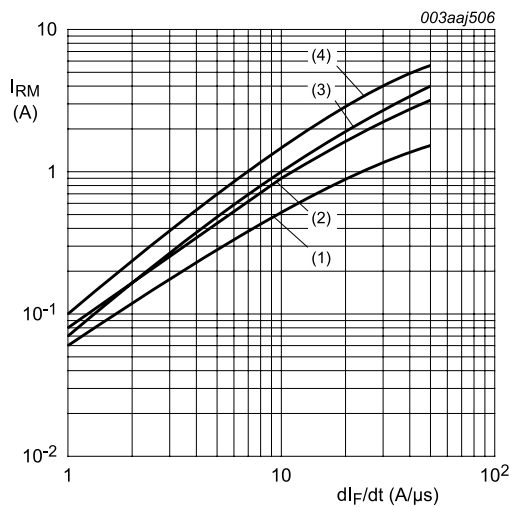


Fig. 6. Reverse recovery definitions; ramp recovery



- (1) $I_F = 1 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$
- (2) $I_F = 1 \text{ A}$; $T_j = 100 \text{ }^\circ\text{C}$
- (3) $I_F = 20 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$
- (4) $I_F = 20 \text{ A}$; $T_j = 100 \text{ }^\circ\text{C}$

Fig. 7. Reverse recovery time as a function of rate of change of forward current; per diode; maximum values



- (1) $I_F = 1 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$
- (2) $I_F = 1 \text{ A}$; $T_j = 100 \text{ }^\circ\text{C}$
- (3) $I_F = 20 \text{ A}$; $T_j = 25 \text{ }^\circ\text{C}$
- (4) $I_F = 20 \text{ A}$; $T_j = 100 \text{ }^\circ\text{C}$

Fig. 8. Peak reverse recovery current as a function of rate of change of forward current; per diode; maximum values

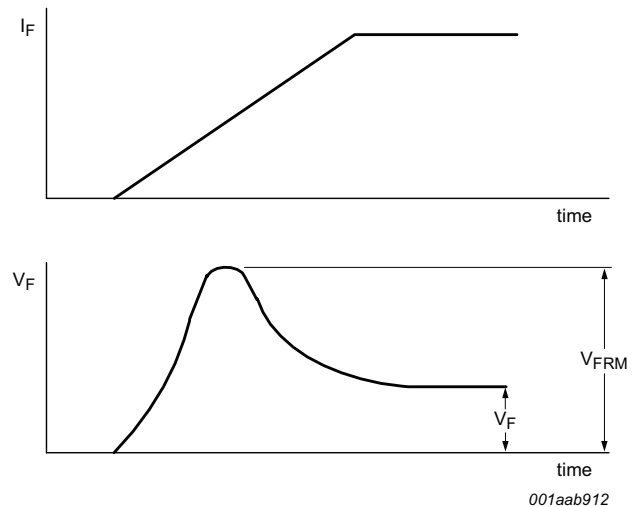


Fig. 9. Forward recovery definitions

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

1. General description..... 1

2. Features and benefits 1

3. Applications 1

4. Quick reference data..... 1

5. Pinning information..... 2

6. Ordering information..... 2

7. Marking..... 2

8. Limiting values 3

9. Thermal characteristics 4

10. Characteristics..... 5

11. Package outline 7

12. Legal information 8

13. Contents 10

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